Title (en)

APPARATUS AND METHOD FOR EMBEDDING COMPONENTS IN SMALL-FORM-FACTOR, SYSTEM-ON-PACKAGES

Title (de)

VORRICHTUNG UND VERFAHREN ZUR EINBETTUNG VON KOMPONENTEN IN SYSTEM-ON-PACKAGES MIT KLEINEM FORMFAKTOR

Title (fr)

APPAREIL ET PROCÉDÉ PERMETTANT D'INTÉGRER DES COMPOSANTS DANS DES SYSTÈMES SUR BOÎTIER À PETIT FACTEUR DE FORME

Publication

EP 2513970 A4 20160511 (EN)

Application

EP 10838087 A 20101117

Priority

- US 64222009 A 20091218
- US 2010057038 W 20101117

Abstract (en)

[origin: US2011147920A1] According to various aspects of the present disclosure, an apparatus is disclosed that includes a small form factor mobile platform including a system-on-package architecture, the system-on-package architecture arranged as a stack of layers including: a first layer having a first conformable material; a second layer having a second conformable material; a third layer having a third material; and one or more electronic components embedded within the stack of layers, wherein the first conformable material, the second conformable material, or both are configured to allow high frequency signal routing.

IPC 8 full level

H01L 23/00 (2006.01); **H01L 23/367** (2006.01); **H01L 23/498** (2006.01); **H01L 23/538** (2006.01); **H01L 23/66** (2006.01); H01L 23/373 (2006.01)

CPC (source: EP US)

H01L 23/3677 (2013.01 - EP US); **H01L 23/373** (2013.01 - EP US); **H01L 23/49822** (2013.01 - EP US); **H01L 23/5389** (2013.01 - EP US); **H01L 23/66** (2013.01 - EP US); **H01L 24/18** (2013.01 - US); **H01L 24/19** (2013.01 - EP US); C09K 2219/03 (2013.01 - EP US); C09K 2219/11 (2013.01 - EP US); H01L 23/3736 (2013.01 - EP US); H01L 24/48 (2013.01 - EP US); H01L 2223/6677 (2013.01 - EP US); H01L 2224/04042 (2013.01 - EP US); H01L 2224/04105 (2013.01 - EP US); H01L 2224/06181 (2013.01 - EP US); H01L 2224/18 (2013.01 - US); H01L 2224/24195 (2013.01 - EP US); H01L 2224/2518 (2013.01 - EP US); H01L 2224/32245 (2013.01 - EP US); H01L 2224/48091 (2013.01 - EP US); H01L 2224/48227 (2013.01 - EP US); H01L 2224/73267 (2013.01 - EP US); H01L 2924/00014 (2013.01 - EP US); H01L 2924/01005 (2013.01 - EP US); H01L 2924/01006 (2013.01 - EP US); H01L 2924/01013 (2013.01 - EP US); H01L 2924/01029 (2013.01 - EP US); H01L 2924/01033 (2013.01 - EP US); H01L 2924/01047 (2013.01 - EP US); H01L 2924/01056 (2013.01 - EP US); H01L 2924/01075 (2013.01 - EP US); H01L 2924/01079 (2013.01 - EP US); H01L 2924/09701 (2013.01 - EP US); H01L 2924/10329 (2013.01 - EP US); H01L 2924/14 (2013.01 - EP US); H01L 2924/1421 (2013.01 - EP US); H01L 2924/15313 (2013.01 - EP US); H01L 2924/19041 (2013.01 - EP US); H01L 2924/3025 (2013.01 - EP US); Y10T 29/49155 (2015.01 - EP US)

Citation (search report)

- [A] US 2008224306 A1 20080918 - YANG WEN-KUN [TW]
- [A] US 5796165 A 19980818 - YOSHIKAWA NORIYUKI [JP], et al
- [I] BAIRAVASUBRAMANIAN R ET AL: "3-D-Integrated RF and Millimeter-Wave Functions and Modules Using Liquid Crystal Polymer (LCP) System-on-Package Technology", IEEE TRANSACTIONS ON ADVANCED PACKAGING, IEEE SERVICE CENTER, PISCATAWAY, NJ, USA, vol. 27, no. 2, May 2004 (2004-05-01), pages 332 - 340, XP011118273, ISSN: 1521-3323, DOI: 10.1109/TADVP.2004.828814
- See references of WO 2011075265A2

Designated contracting state (EPC)

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DOCDB simple family (application)

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